

LEXAN™ COPOLYMER EXL8134

REGION ASIA

DESCRIPTION

LEXAN EXL8134 is a PC/siloxane copolymer resin with high flow, excellent low temperature impact and 30% post consumer recycle content. Limited availability and restricted color only. Higher color variability and contamination risks including black specs needs to be considered before approval for use in applications.

TYPICAL PROPERTY VALUES

Revision 20231109

PROPERTIES	TYPICAL VALUES	UNITS	TEST METHODS
MECHANICAL			
Tensile Stress, yld, Type I, 50 mm/min	57	MPa	ASTM D638
Tensile Stress, brk, Type I, 50 mm/min	55	MPa	ASTM D638
Tensile Strain, yld, Type I, 50 mm/min	6	%	ASTM D638
Tensile Strain, brk, Type I, 50 mm/min	100	%	ASTM D638
Tensile Modulus, 5 mm/min	2200	MPa	ASTM D638
Flexural Stress, yld, 1.3 mm/min, 50 mm span	90	MPa	ASTM D790
Flexural Modulus, 1.3 mm/min, 50 mm span	2100	MPa	ASTM D790
IMPACT			
Izod Impact, notched, 23°C	800	J/m	ASTM D256
Izod Impact, notched, -30°C	700	J/m	ASTM D256
Izod Impact, notched, -40°C	650	J/m	ASTM D256
Instrumented Dart Impact Total Energy, 23°C	70	J	ASTM D3763
THERMAL			
Vicat Softening Temp, Rate B/50	145	°C	ASTM D1525
HDT, 1.82 MPa, 3.2mm, unannealed	123	°C	ASTM D648
CTE, -40°C to 40°C, flow	6.E-05	1/°C	ASTM E831
CTE, -40°C to 40°C, xflow	6.E-05	1/°C	ASTM E831
Relative Temp Index, Elec ⁽¹⁾	80	°C	UL 746B
Relative Temp Index, Mech w/impact ⁽¹⁾	80	°C	UL 746B
Relative Temp Index, Mech w/o impact ⁽¹⁾	80	°C	UL 746B
PHYSICAL			
Specific Gravity	1.2	-	ASTM D792
Mold Shrinkage, flow, 3.2 mm	0.4 – 0.8	%	SABIC method
Melt Flow Rate, 300°C/1.2 kgf	15	g/10 min	ASTM D1238
Water Absorption, 23°C/24hrs	0.15	%	SABIC method
ELECTRICAL			
Volume Resistivity	>1.E+15	Ω.cm	ASTM D257
Surface Resistivity	>1.E+15	Ω	ASTM D257
Dielectric Strength, in oil, 0.8 mm	15	kV/mm	ASTM D149
Relative Permittivity, 1 MHz	3	-	ASTM D150
Dissipation Factor, 1 MHz	0.0092	-	ASTM D150
Hot-Wire Ignition (HWI), PLC 3	≥3	mm	UL 746A
FLAME CHARACTERISTICS ⁽¹⁾			

PROPERTIES	TYPICAL VALUES	UNITS	TEST METHODS
UL Yellow Card Link	E207780-100656422	-	-
UL Recognized, 94HB Flame Class Rating	≥0.75	mm	UL 94
Glow Wire Ignitability Temperature, 3.0 mm	875	°C	IEC 60695-2-13
Glow Wire Ignitability Temperature, 1.5 mm	875	°C	IEC 60695-2-13
Glow Wire Ignitability Temperature, 1.0 mm	875	°C	IEC 60695-2-13
Glow Wire Ignitability Temperature, 0.75 mm	850	°C	IEC 60695-2-13
Glow Wire Flammability Index, 3.0 mm	960	°C	IEC 60695-2-12
Glow Wire Flammability Index, 1.5 mm	850	°C	IEC 60695-2-12
Glow Wire Flammability Index, 1.0 mm	850	°C	IEC 60695-2-12
Glow Wire Flammability Index, 0.75 mm	825	°C	IEC 60695-2-12
INJECTION MOLDING			
Drying Temperature	120	°C	
Drying Time	3 – 4	Hrs	
Drying Time (Cumulative)	48	Hrs	
Maximum Moisture Content	0.02	%	
Melt Temperature	295 – 315	°C	
Nozzle Temperature	290 – 310	°C	
Front - Zone 3 Temperature	295 – 315	°C	
Middle - Zone 2 Temperature	280 – 305	°C	
Rear - Zone 1 Temperature	270 – 295	°C	
Mold Temperature	70 – 95	°C	
Back Pressure	0.3 – 0.7	MPa	
Screw Speed	40 – 70	rpm	
Shot to Cylinder Size	40 – 60	%	
Vent Depth	0.025 – 0.076	mm	

(1) UL Ratings shown on the technical datasheet might not cover the full range of thicknesses and colors. For details, please see the UL Yellow Card.

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